OK TO ENTER: /JC/ (07/02/2008)

Atty. Dkt. No. 039153-0693 (H1718)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Xiang et al.

Title: SHALLOW TRENCH ISOLATION PROCESS AND STRUCTURE WITH MINIMIZED STRAINED SILICON CONSUMPTION

Appl. No.: 10/755,602

Filing Date: 01/12/2004

Examiner: Jack S. J. Chen

Art Unit: 2813

Conf. No.: 9549

AMENDMENT UNDER 37 CFR 1.312

Mail Stop ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Applicant acknowledges receipt of a Notice of Allowance in the above-captioned application. Prior to payment of the issue fee, please amend the application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this document.

Remarks/Arguments begin on page 4 of this document.

Please amend the application as follows: